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**High Strength**  
**Solvent Free**  
**Electrically Conductive**  
**Epoxy Paste Adhesive**

**IDEAL FOR:**

Conventional Die Attach  
 Automated Dispensing

**DESCRIPTION:**

ME8412 is a silver filled, solvent free, electrically and thermally conductive paste. It is designed for automated, online, die attach processing. It is thixotropic and will not sag on vertical surfaces. Designed to meet the hybrid adhesive specification, Mil Std 883; Method 5011.4 in terms of ionic impurities, ME8412 exhibits low outgassing at 125C and passes NASA outgassing requirements.

**AVAILABILITY:**

ME8412 is available in syringes for automatic needle dispense applications or in jars. Viscosity and thixotropic index can be modified to meet customer needs.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 minutes before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to one of the recommended schedules.

**PRIMA-SOLDER**  
**ME8412**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 30 minutes )	<b>&lt;5x10<sup>-4</sup> ohm-cm</b>
Dielectric Strength (Volts/mil)	<b>N/A</b>
Glass Transition Temp.(°C)	<b>130 ±10%</b>
Current Carrying Capabilities	<b>&gt;40 Amp/mm<sup>2</sup></b>
Lap-Shear Strength	<b>&gt;1000 psi &gt;6.9 N/mm<sup>2</sup></b>
Device Push-off Strength	<b>&gt;2000 psi &gt;13.8 N/mm<sup>2</sup></b>
Hardness (Type)	<b>85 (D) ±10%</b>
Cured Density (gm/cc)	<b>3.5 ±10%</b>
Thermal Conductivity	<b>55 Btu-in/hr-ft<sup>2</sup>-°F ±10% 7.9 W/m-°C ±10%</b>
Linear Thermal Expansion Coeff. (ppm/°C)	<b>45 ±15%</b>
Maximum Continuous Operation Temp. (°C)	<b>&lt;150</b>
Pot Life	<b>&gt;180,000cp ±20%</b>
Avg. Viscosity(0.5 rpm, 25°C) (Brookfield DV-1, spindle CP51)	<b>&gt;180,000cp ±20%</b>
Thixotropic Index	

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

Temperature	Time	Pressure
80°C	6 hr	
100°C	3 hr	
125°C	90 min	
150°C	30 min	

**SHELF LIFE:**

Storage temperature	Shelf Life
-40°C	1 yr

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

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